

SUPPLY-CHAIN PERFORMANCE WORKING GROUP MINUTES

Date: March 18, 2009
Location: Teleconference
Time: 11:00am – 12:00pm (PDT)
Participants:

Roger DeAmicis – ChipX
Larry Sladewski – NVIDIA
Eelco Bergman – Vietnam-Chipscale Advanced Packaging Services
Issac Cohen – ASOCS Ltd.
Chelsea Boone – GSA

Meeting Purpose:

- To discuss the Q1 2009 Wafer & Back-End Pricing Survey Results.

Actions Completed/Items Discussed:

- Q1 2009 WP & BE Survey Results
- Future Timelines/Dates for Next Survey

End Result/Conclusions:

- **Q1 2009 WP & BE Survey Results:**
Chelsea will check with PDS why some values were flagged as outliers, when they were within the thresholds. PDS has requested that we provide them with more filters for wafer.
Assembly
-Delete row 30 in spreadsheet
Wafer
-Keep all rows
Mask
-Delete rows 5 & 6 in spreadsheet
- **Future Timelines/Dates for Next Survey:**
 - Q1 2009 Wafer & Back-End Pricing Report Released: 3/27/2009
 - Q2 2009 Wafer & Back-End Pricing Survey Released: 4/1/2009
 - Q2 2009 Wafer & Back-End Pricing Survey Ends: 4/22/2009
 - Q2 2009 Working Group Meeting: Week of 5/6/2009In the next meeting, we need to discuss the Logistics Survey.